

## PATENT ABSTRACTS OF JAPAN

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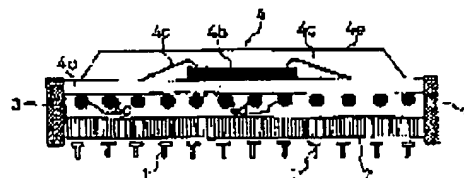
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### (54) TEST SOCKET FOR SEMICONDUCTOR DEVICE

(57)Abstract:

**PURPOSE:** To obtain a test socket in which solder balls are protected against damage or deformation by laying an anisotropic conductive sheet on the upper surface at a contact part.

**CONSTITUTION:** When a BGA package 4 to be tested is mounted, it is inserted into the lower part of a socket while being guided by a positioning guide 3 and then an upper cover of socket is applied and pressed from above the package 4. Consequently, each solder ball 4d is brought into electrical contact with a contact pint 1 through an anisotropic conductive sheet 2. At that time, pressure against the solder ball 4d is lessened through the elasticity of the anisotropic conductive sheet 2. Furthermore, since the anisotropic conductive sheet 2 can be laid removably, only the anisotropic conductive sheet 2 can be replaced at the time of failure without replacing the test socket body thus reducing the labor and cost required for repair.



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